

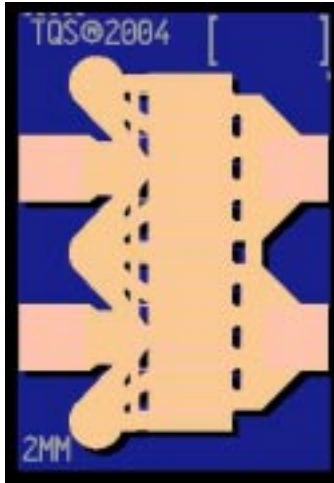


Advance Product Information

September 19, 2005

DC - 12 GHz Discrete power pHEMT

TGF2021-02



Key Features and Performance

- Frequency Range: DC - 12 GHz
- > 33 dBm Nominal Psat
- 59% Maximum PAE
- 11 dB Nominal Power Gain
- Suitable for high reliability applications
- 2mm x 0.35μm Power pHEMT
- Nominal Bias Vd = 8-12V, Idq = 150-250mA (Under RF Drive, Id rises from 150mA to 480mA)
- Chip Dimensions: 0.57 x 0.79 x 0.10 mm (0.022 x 0.031 x 0.004 in)

Product Description

The TriQuint TGF2021-02 is a discrete 2 mm pHEMT which operates from DC-12 GHz. The TGF2021-02 is designed using TriQuint's proven standard 0.35μm power pHEMT production process.

The TGF2021-02 typically provides > 33 dBm of saturated output power with power gain of 11 dB. The maximum power added efficiency is 59% which makes the TGF2021-02 appropriate for high efficiency applications.

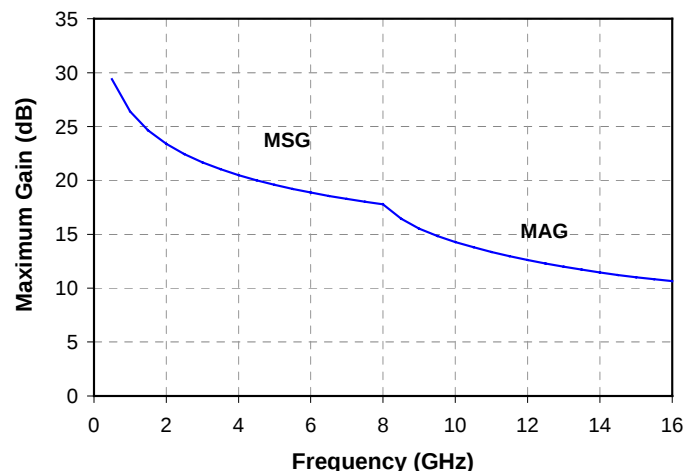
The TGF2021-02 is also ideally suited for Point-to-point Radio, High-reliability space, and Military applications.

The TGF2021-02 has a protective surface passivation layer providing environmental robustness.

Lead-free and RoHS compliant

Primary Applications

- Point-to-point Radio
- High-reliability space
- Military
- Base Stations
- Broadband Wireless Applications



Note: This device is early in the characterization process prior to finalizing all electrical specifications. Specifications are subject to change without notice.



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TABLE I
MAXIMUM RATINGS

Symbol	Parameter <u>1/</u>	Value	Notes
V ⁺	Positive Supply Voltage	12.5 V	<u>2/</u>
V ⁻	Negative Supply Voltage Range	-5V to 0V	
I ⁺	Positive Supply Current	940 mA	<u>2/</u>
I _G	Gate Supply Current	14 mA	
P _{IN}	Input Continuous Wave Power	28 dBm	<u>2/</u>
P _D	Power Dissipation	See note 3	<u>2/ 3/</u>
T _{CH}	Operating Channel Temperature	150 °C	<u>4/</u>
T _M	Mounting Temperature (30 Seconds)	320 °C	
T _{STG}	Storage Temperature	-65 to 150 °C	

- 1/ These ratings represent the maximum operable values for this device.
- 2/ Combinations of supply voltage, supply current, input power, and output power shall not exceed P_D.
- 3/ For a median life time of 1E+6 hrs, Power dissipation is limited to:

$$P_D(\text{max}) = (150\text{ °C} - T_{\text{BASE}}\text{ °C}) / 43.3\text{ (°C/W)}$$
- 4/ Junction operating temperature will directly affect the device median time to failure (T_M). For maximum life, it is recommended that junction temperatures be maintained at the lowest possible levels.

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TABLE II
DC PROBE CHARACTERISTICS
(T_A = 25 °C, Nominal)

Symbol	Parameter	Minimum	Typical	Maximum	Unit
I _{DSS}	Saturated Drain Current	-	600	-	mA
G _m	Transconductance	-	750	-	mS
V _P	Pinch-off Voltage	-1.5	-1	-0.5	V
V _{BGS}	Breakdown Voltage Gate-Source	-30	-	-14	V
V _{BGD}	Breakdown Voltage Gate-Drain	-30	-	-14	V

Note: For TriQuint's 0.35um power pHEMT devices, RF breakdown >> DC breakdown



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TABLE III
RF CHARACTERIZATION TABLE 1/
 (T_A = 25 °C, Nominal)

SYMBOL	PARAMETER	Vd = 10V Idq = 150mA	Vd = 12V Idq = 150mA	UNITS
Power Tuned:				
Psat	Saturated Output Power	33.8	34.5	dBm
PAE	Power Added Efficiency	50	48	%
Gain	Power Gain	11	11	dB
Rp <u>2/</u>	Parallel Resistance	13.30	15.97	Ω
Cp <u>2/</u>	Parallel Capacitance	0.927	0.953	pF
Γ _L <u>3/</u> , <u>4/</u>	Load Reflection coefficient	0.719 ∠ 164.9	0.720 ∠ 161.4	-
Efficiency Tuned:				
Psat	Saturated Output Power	33	33.7	dBm
PAE	Power Added Efficiency	59	55	%
Gain	Power Gain	11.5	11	dB
Rp <u>2/</u>	Parallel Resistance	24.50	27.79	Ω
Cp <u>2/</u>	Parallel Capacitance	1.077	1.011	pF
Γ _L <u>3/</u> , <u>4/</u>	Load Reflection coefficient	0.778 ∠ 155.2	0.774 ∠ 152.7	-

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1/ Values in this table are scaled from measurements taken from a 1mm unit pHEMT cell at 10 GHz

2/ Large signal equivalent pHEMT output network

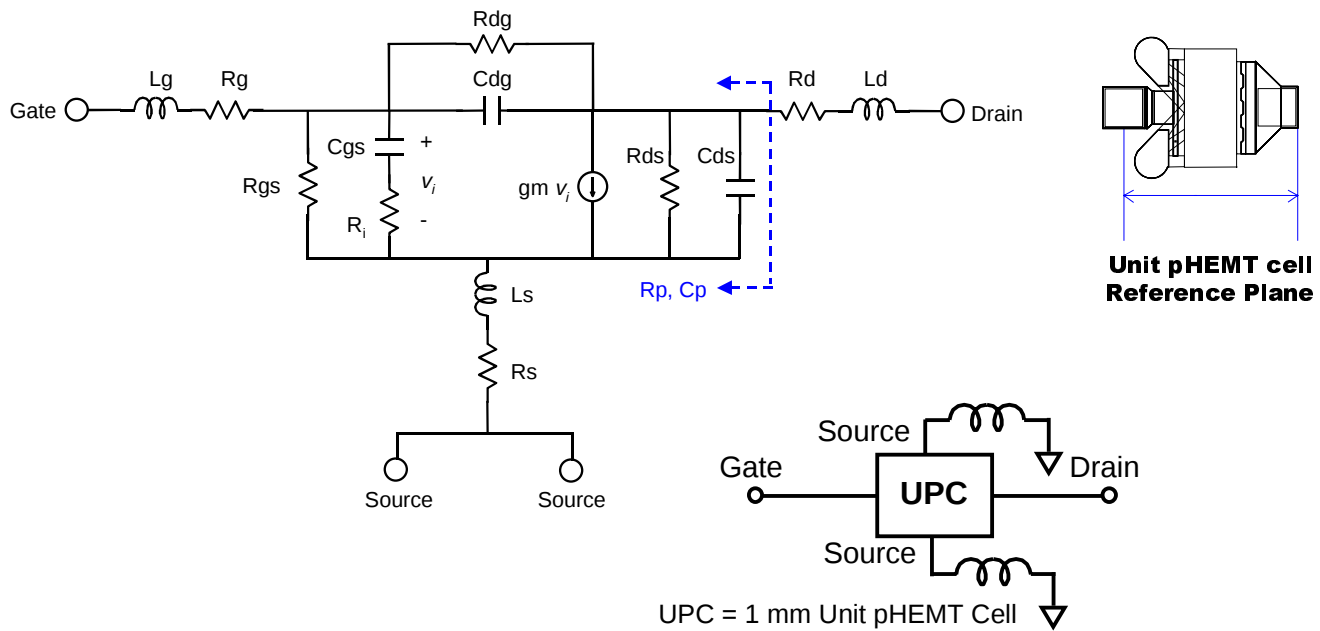
3/ Optimum load impedance for maximum power or maximum PAE at 10 GHz

4/ The reflection coefficients for this device have been calculated from the scaled large signal Rp & Cp.
 The series resistance and inductance (Rd and Ld) shown in the Figure on page 4 is excluded

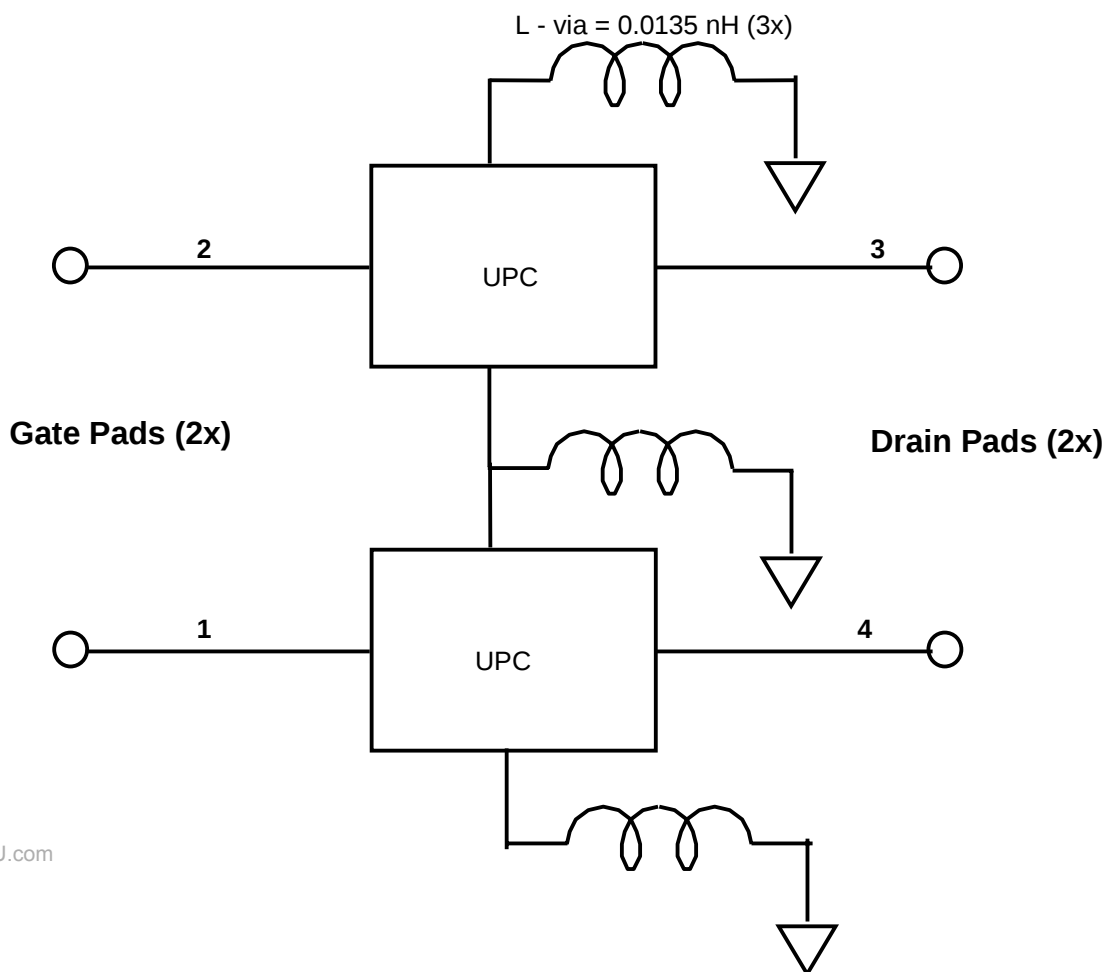
TABLE IV
THERMAL INFORMATION

Parameter	Test Conditions	T _{CH} (°C)	θ _{JC} (°C/W)	T _M (HRS)
θ _{JC} Thermal Resistance (channel to backside of carrier)	Vd = 12 V Idq = 150 mA P _{diss} = 1.8 W	148	43.3	1.2 E+6

Note: Assumes eutectic attach using 1.5 mil 80/20 AuSn mounted to a 20 mil CuMo Carrier at 70°C baseplate temperature.

Linear Model for 1mm Unit pHEMT cell


MODEL PARAMETER	Vd = 8V Idq = 75mA	Vd = 8V Idq = 100mA	Vd = 8V Idq = 125mA	Vd = 10V Idq = 75mA	Vd = 10V Idq = 100mA	Vd = 12V Idq = 75mA	UNITS
Rg	0.45	0.45	0.45	0.45	0.450	0.45	Ω
Rs	0.14	0.14	0.14	0.17	0.160	0.19	Ω
Rd	0.41	0.43	0.46	0.41	0.450	0.410	Ω
gm	0.310	0.318	0.314	0.296	0.303	0.286	S
Cgs	2.39	2.58	2.70	2.61	2.74	2.72	pF
Ri	1.22	1.19	1.20	1.24	1.23	1.27	Ω
Cds	0.20	0.201	0.201	0.198	0.199	0.196	pF
Rds	149.1	152.3	158.8	171.8	173.7	187.9	Ω
Cgd	0.115	0.107	0.101	0.101	0.098	0.096	pF
Tau	6.29	6.63	6.99	7.19	7.410	7.79	pS
Ls	0.009	0.009	0.009	0.009	0.010	0.010	nH
Lg	0.089	0.089	0.089	0.089	0.089	0.089	nH
Ld	0.120	0.120	0.120	0.120	0.120	0.120	nH
Rgs	33000	33000	35100	28900	35700	24400	Ω
Rgd	349000	425000	405000	305000	366000	238000	Ω

Linear Model for 2mm pHEMT



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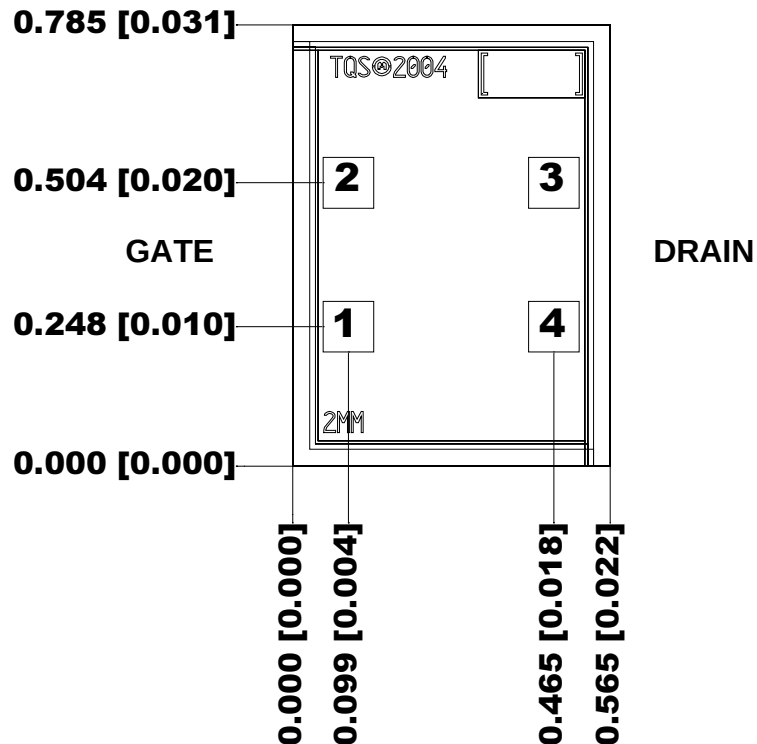
Unmatched S-parameter for 2mm pHEMT

Bias Conditions: Vd=12V, Idq=150mA

Frequency (GHz)	s11 dB	s11 ang deg	s21 dB	s21 ang deg	s12 dB	s12 ang deg	s22 dB	s22 ang deg
0.5	-0.444	-108.860	26.175	121.91	-32.618	34.41	-11.025	-98.11
1	-0.572	-140.91	21.362	103.42	-31.423	18.42	-11.493	-127.41
1.5	-0.605	-153.69	18.095	94.44	-31.187	11.96	-11.428	-137.24
2	-0.616	-160.46	15.676	88.41	-31.135	8.45	-11.181	-140.97
2.5	-0.620	-164.67	13.761	83.63	-31.146	6.22	-10.844	-142.33
3	-0.621	-167.58	12.175	79.50	-31.191	4.65	-10.455	-142.71
3.5	-0.619	-169.72	10.819	75.76	-31.257	3.50	-10.037	-142.70
4	-0.617	-171.39	9.632	72.27	-31.340	2.63	-9.606	-142.57
4.5	-0.613	-172.74	8.574	68.95	-31.437	1.98	-9.173	-142.48
5	-0.610	-173.86	7.619	65.77	-31.546	1.49	-8.745	-142.47
5.5	-0.605	-174.82	6.745	62.70	-31.666	1.16	-8.329	-142.57
6	-0.600	-175.66	5.939	59.71	-31.795	0.96	-7.926	-142.80
6.5	-0.595	-176.41	5.190	56.80	-31.933	0.89	-7.540	-143.14
7	-0.589	-177.09	4.488	53.96	-32.077	0.95	-7.172	-143.58
7.5	-0.584	-177.71	3.828	51.18	-32.228	1.13	-6.821	-144.12
8	-0.578	-178.28	3.203	48.45	-32.384	1.44	-6.489	-144.73
8.5	-0.572	-178.81	2.610	45.78	-32.543	1.87	-6.174	-145.42
9	-0.566	-179.32	2.044	43.16	-32.704	2.42	-5.876	-146.17
9.5	-0.559	-179.80	1.503	40.59	-32.865	3.11	-5.595	-146.97
10	-0.553	-179.75	0.984	38.06	-33.025	3.92	-5.330	-147.81
10.5	-0.547	-179.31	0.485	35.58	-33.182	4.85	-5.079	-148.69
11	-0.541	-178.88	0.005	33.15	-33.333	5.92	-4.842	-149.59
11.5	-0.535	-178.47	-0.459	30.75	-33.478	7.10	-4.619	-150.52
12	-0.528	-178.08	-0.908	28.40	-33.614	8.41	-4.409	-151.46
12.5	-0.522	-177.69	-1.343	26.09	-33.738	9.83	-4.210	-152.42
13	-0.516	-177.31	-1.765	23.82	-33.849	11.36	-4.022	-153.39
13.5	-0.510	-176.94	-2.175	21.59	-33.946	12.98	-3.844	-154.36
14	-0.505	-176.57	-2.574	19.39	-34.026	14.69	-3.677	-155.34
14.5	-0.499	-176.21	-2.963	17.23	-34.088	16.48	-3.518	-156.32
15	-0.493	-175.86	-3.341	15.10	-34.130	18.32	-3.368	-157.29
15.5	-0.488	-175.51	-3.710	13.01	-34.153	20.21	-3.226	-158.27
16	-0.483	-175.16	-4.071	10.95	-34.154	22.13	-3.091	-159.24
16.5	-0.477	-174.82	-4.424	8.93	-34.135	24.06	-2.964	-160.21
17	-0.472	-174.49	-4.769	6.93	-34.095	25.99	-2.843	-161.17
17.5	-0.467	-174.15	-5.107	4.97	-34.035	27.90	-2.728	-162.13
18	-0.463	-173.82	-5.439	3.03	-33.956	29.77	-2.619	-163.07
18.5	-0.458	-173.49	-5.764	1.13	-33.859	31.60	-2.515	-164.02
19	-0.453	-173.17	-6.083	-0.75	-33.745	33.37	-2.416	-164.95
19.5	-0.449	-172.85	-6.396	-2.61	-33.615	35.08	-2.323	-165.87
20	-0.445	-172.53	-6.704	-4.44	-33.473	36.72	-2.233	-166.79
20.5	-0.441	-172.21	-7.007	-6.24	-33.318	38.28	-2.148	-167.69
21	-0.437	-171.89	-7.306	-8.03	-33.153	39.75	-2.067	-168.59
21.5	-0.433	-171.58	-7.600	-9.79	-32.979	41.15	-1.989	-169.48
22	-0.429	-171.26	-7.890	-11.53	-32.798	42.46	-1.915	-170.36
22.5	-0.425	-170.95	-8.176	-13.25	-32.611	43.68	-1.845	-171.23
23	-0.422	-170.64	-8.459	-14.95	-32.419	44.83	-1.777	-172.10
23.5	-0.418	-170.34	-8.738	-16.63	-32.224	45.89	-1.713	-172.95
24	-0.415	-170.03	-9.015	-18.29	-32.026	46.87	-1.651	-173.79
24.5	-0.412	-169.72	-9.288	-19.94	-31.826	47.79	-1.591	-174.63
25	-0.409	-169.42	-9.559	-21.57	-31.626	48.63	-1.534	-175.46
25.5	-0.406	-169.12	-9.828	-23.19	-31.426	49.40	-1.480	-176.28
26	-0.403	-168.82	-10.094	-24.79	-31.226	50.10	-1.427	-177.09

Note: The s-parameters are calculated by connecting nodes 1-2 together, and nodes 3-4 together to form a 2-port network.

Mechanical Drawing



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Units: millimeters (inches)
Thickness: 0.100 (0.004)
Chip edge to bond pad dimensions are shown to center of bond pad
Chip size tolerance: +/- 0.051 (0.002)
GND IS BACKSIDE OF MMIC
Bond pads #1-2: (Gate) 0.090 x 0.090 (0.004 x 0.004)
Bond pads #3-4: (Drain) 0.090 x 0.090 (0.004 x 0.004)

GaAs MMIC devices are susceptible to damage from Electrostatic Discharge. Proper precautions should be observed during handling, assembly and test.



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Assembly Process Notes

Reflow process assembly notes:

- Use AuSn (80/20) solder with limited exposure to temperatures at or above 300 °C for 30 sec
- An alloy station or conveyor furnace with reducing atmosphere should be used.
- Do not use flux
- Coefficient of thermal expansion matching is critical for long-term reliability.
- Devices must be stored in a dry nitrogen atmosphere.

Component placement and adhesive attachment assembly notes:

- Vacuum pencils and/or vacuum collets are the preferred method of pick up.
- Air bridges must be avoided during placement.
- The force impact is critical during auto placement.
- Organic attachment can be used in low-power applications.
- Curing should be done in a convection oven; proper exhaust is a safety concern.
- Microwave or radiant curing should not be used because of differential heating.
- Coefficient of thermal expansion matching is critical.

Interconnect process assembly notes:

- Thermosonic ball bonding is the preferred interconnect technique.
- Force, time, and ultrasonics are critical parameters.
- Aluminum wire should not be used.
- Devices with small pad sizes should be bonded with 0.0007-inch wire.
- Maximum stage temperature is 200 °C.